Date: 2-7-05

By: Sai Nicto

Signature of Person Depositing Facsimile

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

P. 06/17

Applicant(s):

Lunde

Atty. Docket No .:

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. Nguyen, Khiem D.

Group Art Unit:

2823

Confirmation No.:

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Title:

A DIE ASSEMBLY AND METHOD FOR FORMING A DIE ON A WAFER

RESPONSE AND AMENDMENT

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Commissioner:

In response to the Final Office Action dated March 5, 2004, Applicants hereby submit

a Request for Continued Examination along with the appropriate fee. Applicants also respond as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.

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